### The FET Constant-Current Source/Limiter

#### Introduction

The combination of low associated operating voltage and high output impedance makes the FET attractive as a constant-current source. An adjustable-current source (Figure 1) may be built with a FET, a variable resistor, and a small battery. For optimum thermal stability, the FET should be biased near the zero temperature coefficient point.

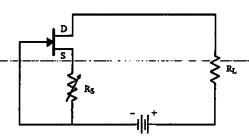


Figure 1. Field-Effect Transistor Current Source

Whenever the FET is operated in the current saturated region, its output conductance is very low. This occurs whenever the drain-source voltage  $V_{DS}$  is at least 50% greater than the cut-off voltage  $V_{GS(\alpha\Omega)}$ . The FET may be biased to operate as a constant-current source at any current below its saturation current  $I_{DSS}$ .

### **Basic Source Biasing**

For a given device where IDSS and VGS(off) are known, the approximate VGS required for a given ID is

$$V_{GS} = V_{GS(off)} \left[ 1 - \left( \frac{l_D}{l_{DSS}} \right)^{1/\lambda} \right]$$
 (1)

where k can vary from 1.8 to 2.0, depending on device geometry. If K=2.0, the series resistor  $R_{\rm S}$  required between source and gate is

$$R_{s} = \frac{V_{GS}}{l_{D}} \quad \text{or} \quad R_{s} = \frac{V_{GS(off)}}{l_{D}} \left( 1 - \sqrt{\frac{l_{D}}{l_{DSS}}} \right)$$
 (2)

A change in supply voltage or a change in load impedance, will change  $I_{\rm D}$  by only a small factor because of the low output conductance  $g_{oss}$ .

$$\Delta I_D = (\Delta V_{DS})(g_{OSS}) \tag{3}$$

The value of  $g_{OSS}$  is an important consideration in the accuracy of a constant-current source where the supply voltage may vary. As  $g_{OSS}$  may range from less than 1  $\mu S$  to more than 50  $\mu S$  according to the FET type, the dynamic impedance can be greater than 1  $M\Omega$  to less than 20  $k\Omega$ . This corresponds to a current stability range of 1  $\mu A$  to 50  $\mu A$  per volt. The value of  $g_{OSS}$  also depends on the operating point. Output conductance  $g_{OSS}$  decrease approximately linearly with ID. The relationship is

$$\frac{I_{D}}{I_{DOS}} = \frac{g_{OSL}}{g'_{OSL}} \tag{4}$$

where 
$$g_{oss} = g'_{oss}$$
 (5)

when 
$$V_{GS} = 0$$
 (6)

So as  $V_{GS} \rightarrow V_{GS(off)}$ ,  $g_{oss} \rightarrow Z_{CFO}$ . For best regulation,  $I_D$  must be considerably less than  $I_{DSS}$ .

### Cascading for Low goss

It is possible to achieve much lower goss per unit ID by cascading two FETs, as shown in Figure 2.

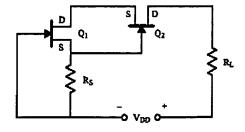


Figure 2. Cascade FET Current Source

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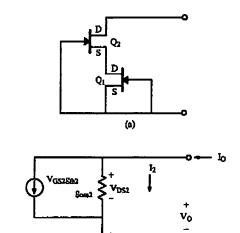


Figure 3. Cascade FET VGS1 = 0

**(b)** 

 $V_{DS1} = -V_{CIS2}$ 

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Now,  $I_D$  is regulated by  $Q_1$  and  $V_{DS1} = -V_{GS2}$ . The dc value of  $I_D$  is controlled by  $R_S$  and  $Q_1$ . However,  $Q_1$  and  $Q_2$  both affect current stability. The circuit output conductance is derived as follows:

$$g_{\phi} = \frac{g_{oes}}{2 + \frac{g_{a}}{E_{des}}} \tag{8}$$

when RS = 0 as in Figure 2

$$g_o = \frac{g_{ob}^2}{g_o[1 + R_o g_o]} \tag{9}$$

In either case ( $R_S = 0$  or  $R_S \neq 0$ ), the circuit output conductance is considerably lower than the  $g_{oss}$  of a single FET.

In designing any cascaded FET current source, both FETs must be operated with adequate drain-gate voltage,  $V_{\rm DG}$ . That is,

$$V_{DG} > V_{GS(off)}$$
, preferably  $V_{DG} > 2V_{GS(off)}$  (10)

If VDG < 2 VGS(off), the goss will be significantly increased, and circuit go will deteriorate. For example: A

JFET may have a typical  $g_{OSS} = 4 \mu S$  at  $V_{DS} = 20 \text{ V}$  and  $V_{GS} = 0$ . At  $V_{DS} \sim -V_{GS(off)} = 2 \text{ V}$ ,  $g_{OSS} \sim 100 \mu S$ .

The best FETs for current sources are those having long gates and consequently very low  $g_{OSS}$ . The Siliconix 2N4340, J202, and SST202 exhibit typical  $g_{OSS}=2~\mu S$  at  $V_{DS}=20~V$ . These devices in the circuit of Figure 4 will provide a current source adjustable from 5  $\mu A$  to 0.8 mA with internal impedance greater than 2 M $\Omega$  at 0.2 mA. Other Siliconix part types such as the 2N4392, J112, and SST112 can provide 10 mA or higher current.

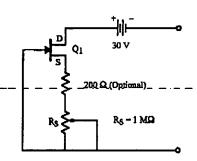


Figure 4. Adjustable Current Source  $R_S = 1 M\Omega$ 

Instead of the adjustable resistor, the JFETs can be put in  $I_{DSS}$  range groupings with an appropriate  $R_{\rm S}$  resistor selected for each group. This method is common in high volume applications.

The cascade circuit of Figure 5 provides a current adjustable from 2  $\mu A$  to 0.8 mA with internal resistance greater than 10 M $\Omega$ .

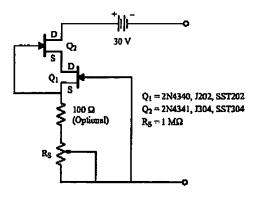


Figure 5. Cascade FET Current Source

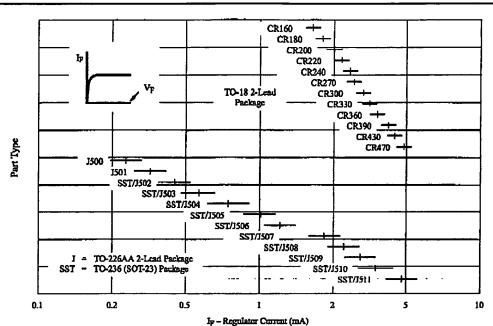


Figure 6. Standard Series Current Regulator Range

### Standard Two-Leaded Devices

Siliconix offers a special series of two-leaded JFETs with a resistor fabricated on the device, thus creating a  $\pm 10\%$  current range. Devices are available in ranges from 1.6 mA (CR160) to 4.7 mA (CR470).

For designs requiring a ±20% current range, Siliconix offers devices rated from 0.24 thA typical (J500) through 4.7 mA typical (J511) in a two-leaded TO-226A (TO-92) package. The SST502 series is available in surface mount TO-236 (SOT-23).

Each of these two-leaded devices can be used to replace several typical components.

Figure 6 shows the current ranges of these two device series. Further information is contained in the individual data sheets appearing elsewhere in this data book or from Siliconix FaxBack.

The CR160 series features guaranteed peak operating voltage minimum of 100 V with a typical of 180 V. The J500 scries features 50 V minimum with a typical of 100 V. The lower current devices in both series provide excellent current regulation down to as little as 1 V.

### **Bias Resistor Selection**

All industry JFET part types exhibit a significant variation in  $I_{DSS}$  and  $V_{GS(off)}$  on min/max specifications and device-to-device variations.

Using the simple source biasing current source as illustrated in Figure 1, the designer can graphically calculate the R<sub>S</sub> which best fits the desired drain current I<sub>D</sub>. Figure 7 plotting I<sub>D</sub> versus V<sub>GS</sub> over the military temperature range shows the resulting I<sub>D</sub> for different values of R<sub>S</sub>.

The  $R_S$  lines are constructed by drawing the slope of the  $R_S$  desired value starting at the origin, eg.  $R_S = 2$  k slope. Find a convenient point on the X - Y axis to mark a

$$\frac{V_{GS}}{l_D}$$
 of 2 k $\Omega$  such as  $V_{GS}$  = –1.5 V and  $I_D$  = 0.75 mA.

Then, draw a straight line from this point to the origin. The intersection of this  $R_{\rm S}$  line and the device  $I_{\rm D}$  versus  $V_{\rm GS}$  will be the operating  $I_{\rm D}$ . In this example, the resulting  $I_{\rm D}=0.35$  mA at  $T_{\rm J}=25$ °C. The intercepts of the  $T_{\rm J}=-55$ °C and 125°C show the minimal variation with temperature.

Also note that JFETs have a  $I_D$  current where there is no change with temperature variation. To achieve this  $0T_C$ , the  $-V_{GS}$  voltage  $(I_D \times R_S)$  is approximately:

$$V_{\text{OS(OTC)}} = V_{\text{GS(off)}} - 0.65 V \tag{11}$$

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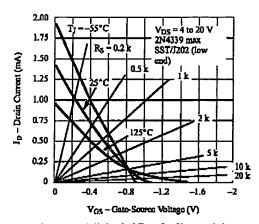


Figure 7. JPET Typical Transfer Characteristic

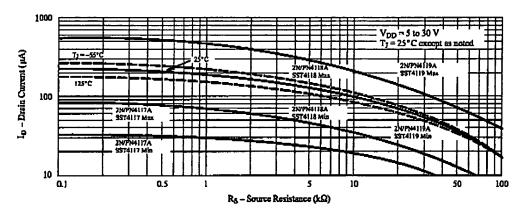


Figure 8. Source Biased Drain-Current vs. Source Resistance

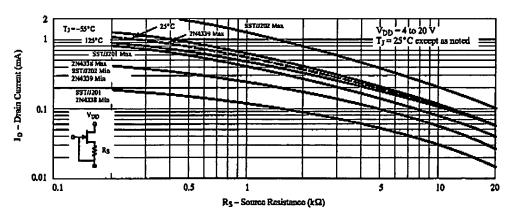


Figure 9. JFET Source Biased Drain-Current vs. Source Resistance

# Choosing the Correct JFET for Source Biasing

Each of the Siliconix device data sheets include typical transfer curves that can be used as illustrated in Figure 7.

Several popular devices are ideal for source biased current sources covering a few  $\mu$ As to 20 mA. To aid the designer, the devices in Table 1 have been plotted to show the drain current, I<sub>D</sub>, versus the source resistance, R<sub>S</sub>, in Figures 8, 9, and 10. Most plots include the likely worst case I<sub>D</sub> variations for a particular R<sub>S</sub>. For tighter current control, the JFET production lot can be divided into ranges with an appropriate resistor selection for each range.

Table 1: Source Bissing Device Recommendations

| Practical<br>Current<br>Range I <sub>D</sub><br>(mA) | Through-Hole<br>Plastic Device | Surface<br>Mount<br>Device | Metal Can<br>Device |
|--|--------------------------------|----------------------------|---------------------|
| 0.01 - 0.02  | PN4117A                        | SST4117                    | 2N4117A             |
| 0.01 - 0.04  | PN4118A                        | SST4118                    | ZN4118A             |
| 0.02 - 0.1   | PN4U9A                         | SST4119                    | 2N4119A             |
| 0.01 - 0.1   | J201                           | SST201                     | ZN4338              |
| 0.02 - 0.3   | J202                           | SST202                     | 2N4339              |
| 0.1 - 2  | Л13                            | SST113                     | 2N4393              |
| 0.2 – 10   | J112                           | SST112                     | ZN4392              |

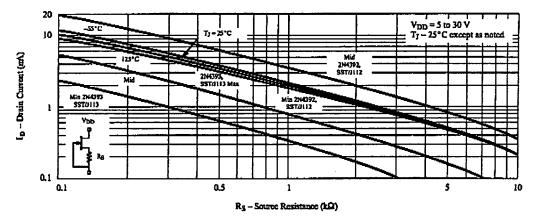


Figure 10. JFET Source Biased Drain-Current vs. Source Resistance